

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XCL219xxxxFR-G
Typical mass: 22.0 mg

Part	Part name	Weight(mg)	Material name	Ratio(ppm)	CAS No.
Coil	Core (Ferrite)	11.450	Iron oxide	520500	1309-37-1
		2.257	Zinc oxide	102600	1314-13-2
		2.199	Nickel oxide	99900	1313-99-1
		0.623	Copper oxide	28300	1317-38-0
		0.078	Tin oxide	3500	18282-10-5
	Internal conductor	0.418	Silver	19000	7440-22-4
	Electrode	0.477	Silver	21700	7440-22-4
		0.175	Nickel	8000	7440-02-0
	0.224	Tin	10200	7440-31-5	
Adhesive Resin	Adhesive Resin	0.068	Epoxy resin	3100	-
		0.016	Organic filler	700	-
		0.016	Inorganic filler	700	-
IC	Silicon chip	0.421	Silicon	19200	7440-21-3
		-	Arsenic	<1	7440-38-2
	Lead pad	1.276	Nickel	58000	7440-02-0
		0.121	Silver	5500	7440-22-4
		0.014	Gold	600	7440-57-5
	Die attach	0.025	Epoxy resin	1200	-
		0.019	Silica	900	14808-60-7
	Bonding wire	0.139	Gold	6300	7440-57-5
	Resin	1.314	Silica	59700	60676-86-0
		0.186	Epoxy resin	8500	-
	0.186	Phenol resin	8500	-	
	0.255	Metal hydroxide	11600	-	
	0.042	Silica (crystal)	1900	14808-60-7	

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."